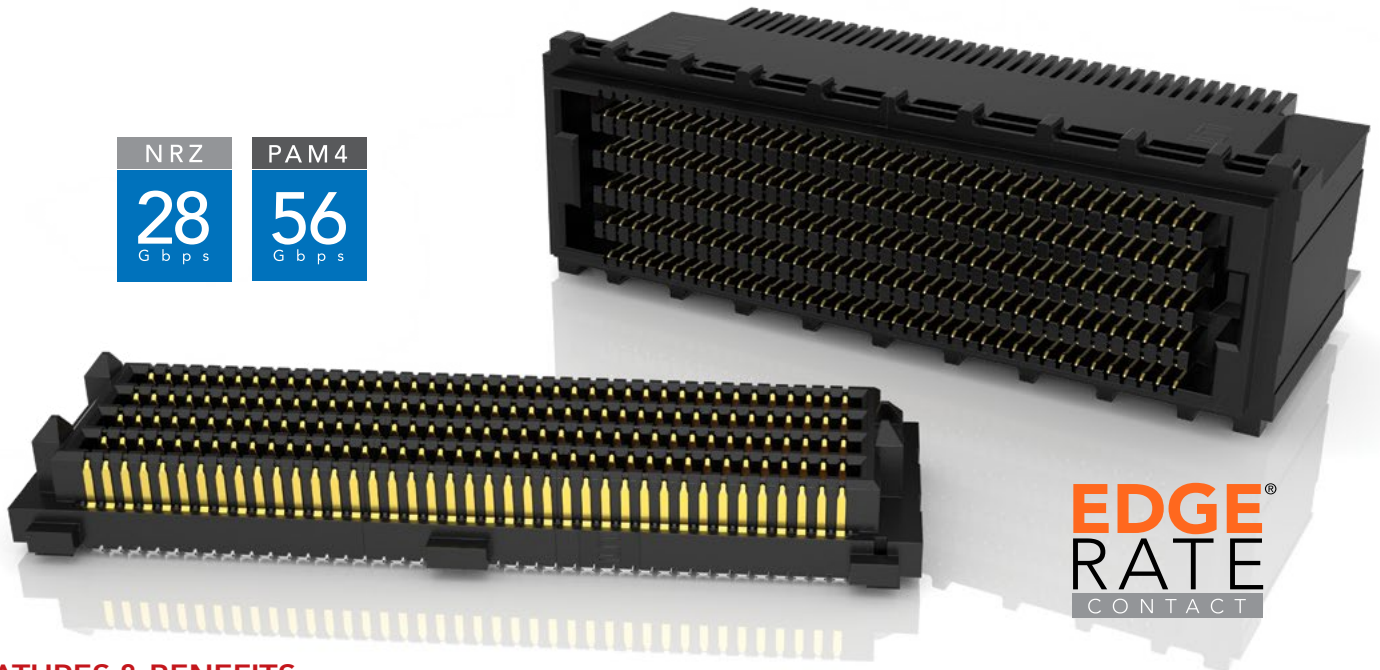


SEARAYTM.8mm

ULTRA HIGH-DENSITY, HIGH-SPEED OPEN-PIN-FIELD ARRAYS

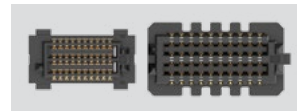
(0.80 mm) .0315" PITCH



| | |
|------------|------------|
| NRZ | PAM4 |
| 28 Gbps | 56 Gbps |

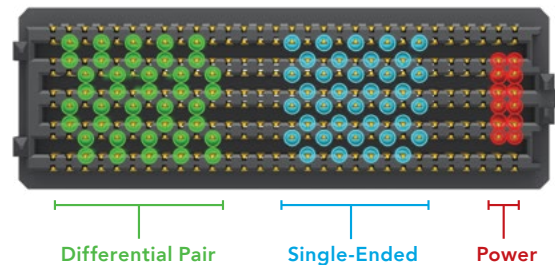
FEATURES & BENEFITS

- 0.80 mm (.0315") pitch grid
- 50% board space savings versus .050" (1.27 mm) pitch arrays
- Performance up to 28 Gbps NRZ/56 Gbps PAM4
- Rugged Edge Rate[®] contact system
- Up to 720 I/Os
- 7 mm and 10 mm stack heights
- Solder charge terminations for ease of processing
- Lower insertion/withdrawal forces



0.80 mm pitch vs. 1.27 mm pitch
(actual size shown; 60 pins)

MAXIMUM GROUNDING & ROUTING FLEXIBILITY



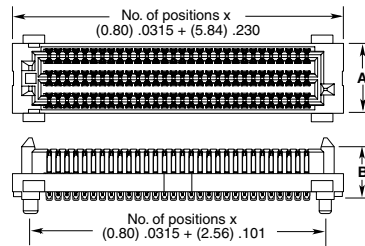
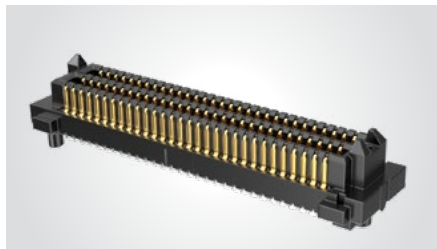
KEY SPECIFICATIONS

| PITCH | STACK HEIGHTS | TOTAL PINS | INSULATOR MATERIAL | CONTACT MATERIAL | PLATING | CURRENT RATING | LEAD-FREE SOLDERABLE |
|---------|---------------|----------------|--------------------|------------------|----------------------------------|--|----------------------|
| 0.80 mm | 7 mm & 10 mm | up to 720 I/Os | Black LCP | Copper Alloy | Au or Sn over 50 μ" (1.27 μm) Ni | 1.3 A per pin (10 adjacent pins powered) | Yes |

(0.80 mm) .0315" PITCH • ULTRA HIGH-DENSITY ARRAYS

| SERIES | NO. PINS PER ROW | LEAD STYLE | PLATING OPTION | NO. OF ROWS | SOLDER TYPE | OPTION | K | "X"R |
|--------------------------|--|---|---|--|--|--|---|--|
| SEAM8 Terminal | -10, -20, -30, -40, -50 | -S02.0 = 2 mm Body Height (SEAM8 only) | -L = 10 μ" (0.25 μm) Gold on contact area, Matte Tin on solder tail | -04 -06 -08 -10 | -1 = Tin/Lead Alloy Solder Crimp | -GP = Guide Post (-S02.0 lead style only) (Mates with SEAF8-RA-GP) | Leave blank for SEAM8 -K = Polyimide film Pick & Place Pad | Tape & Reel is standard. Leave blank for Tape & Reel. -FR = Full Reel Tape & Reel (must order max. quantity per reel; contact Samtec for quantity breaks) |
| SEAF8 Socket | | -S05.0 = 5 mm Body Height (SEAM8 only) | -S = 30 μ" (0.76 μm) Gold on contact area, Matte Tin on solder tail | | -2 = Lead-Free Solder Crimp | | | |

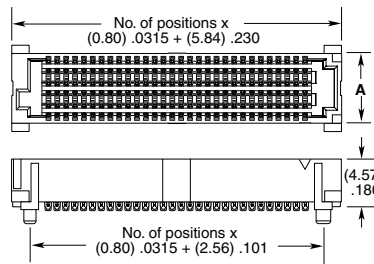
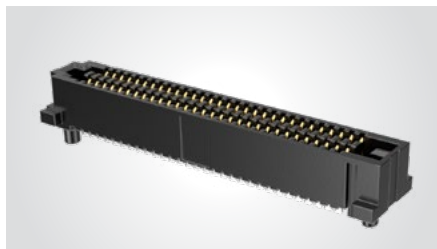
SEAM8
Board Mates:
SEAF8
Cable Mates:
ESCA
Standoffs:
JSO



| NO. OF ROWS | A |
|-------------|--------------|
| -04 | (4.30) .169 |
| -06 | (6.30) .248 |
| -08 | (8.30) .327 |
| -10 | (10.30) .406 |

| LEAD STYLE | B |
|------------|-------------|
| -S02.0 | (4.54) .179 |
| -S05.0 | (7.54) .297 |

SEAF8
Board Mates:
SEAM8
Cable Mates:
ESCA
Standoffs:
JSO



| MATED HEIGHTS* | | |
|------------------|------------------|--------------|
| SEAF8 LEAD STYLE | SEAM8 LEAD STYLE | |
| | -S02.0 | -S05.0 |
| -05.0 | (7.00) .276 | (10.00) .394 |

*Processing conditions will affect mated height.

View complete specifications at: samtec.com?SEAF8

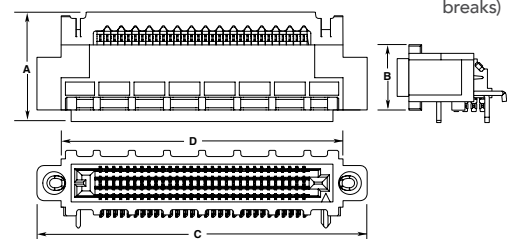
| SEAF8 | NO. PINS PER ROW | 1 | PLATING OPTION | NO. OF ROWS | SOLDER TYPE | RA | OPTION | "X"R |
|-------|-------------------------------------|---|---|--------------------------|--|----|----------------------------------|---|
| | -20, -30, -40, -50 | | -L = 10 μ" (0.25 μm) Gold on contact area, Matte Tin on solder tail | -08 -10 | -1 = Tin/Lead Alloy Solder Crimp | | -GP = Guide Post Holes | Tape & Reel is standard. Leave blank for Tape & Reel. |
| | | | -S = 30 μ" (0.76 μm) Gold on contact area, Matte Tin on solder tail | | -2 = Lead-Free Solder Crimp | | | -FR = Full Reel Tape & Reel (must order max. quantity per reel; contact Samtec for quantity breaks) |

PRELIMINARY

SEAF8-RA
(Right-angle)
Board Mates:
SEAM8
Cable Mates:
ESCA



| NO. PINS PER ROW | C | D |
|------------------|---------------|---------------|
| -20 | (29.62) 1.166 | (24.12) .950 |
| -30 | (37.62) 1.481 | (32.12) 1.265 |
| -40 | (45.62) 1.796 | (40.12) 1.580 |
| -50 | (53.62) 2.111 | (48.12) 1.894 |



Notes:
Some sizes, styles and options are non-standard, non-returnable

View complete specifications at: samtec.com?SEAF8-RA